CLAIMS

1. A circuit member, comprising:

an element having a functional region;

a cover disposed opposite to the functional region; and

a rib formed to surround the functional region, for providing a space between the functional region and the cover,

the cover being tabular and including a sheet S having a thickness of 100μm or less,

the sheet S having a tensile elastic modulus Es at 175°C of 10GPa or more.

2. The circuit member of claim 1, wherein the tensile elastic modulus Es at 175°C of the sheet S is 20GPa or more.

3. The circuit member of claim 1 or 2, further comprising an adhesion layer A provided on at least part of an abutment surface between the element and the rib, and/or on at least part of an abutment surface between the cover and the rib.

4. The circuit member of claim 3, wherein the adhesion layer A has a tensile elastic modulus Ea at 175°C of 10MPa or more.

5. The circuit member of claim 3 or 4, wherein the adhesion layer A has a glass transition temperature Tga of 80°C or more.

6. The circuit member of any one of claims 3 to 5, wherein the adhesion layer A contains a thermosetting resin in a cured state.

7. The circuit member of any one of claims 3 to 6, wherein:

the adhesion layer A is provided on at least part of the abutment surface between the cover and the rib; and

under a temperature condition equal to or lower than the glass transition temperature Tga of the adhesion layer A,

the adhesion layer A has a linear expansion coefficient CTEa of 60ppm/°C or less, and

a difference between the linear expansion coefficient CTEa of the adhesion layer A and a linear expansion coefficient CTEs of the sheet S is 50ppm/°C or less.

8. The circuit member of any one of claims 1 to 7, wherein a material of the sheet S is at least one selected from the group consisting of ceramics, silicon, glass, glass fiber-reinforced resin, and metal.

9. The circuit member of claim 8, wherein the material of the sheet S is the glass.

10. The circuit member of claim 8, wherein the material of the sheet S is the glass fiber-reinforced resin.

11. The circuit member of any one of claims 1 to 10, further comprising a resin encapsulant encapsulating the circuit member.

12. A sheet material for forming a cover of a circuit member, the circuit member comprising:

an element having a functional region;

the cover disposed opposite to the functional region; and

a rib formed to surround the functional region, for providing a space between the functional region and the cover,

the cover being tabular and including a sheet having a thickness of 100μm or less,

the sheet S having a tensile elastic modulus Es at 175°C of 10GPa or more;

wherein the sheet material comprises an adhesion layer AP wherein the adhesion layer AP contains thermossetting resin in an uncured or semi-cured state , and wherein

under a temperature condition equal to or higher than room temperature and equal to or lower than a curing temperature of the adhesion layer AP,

the adhesion layer AP has a storage shear modulus Ga’ of 0.05 to 10MPa, and

a ratio: Ga”/Ga’ of a loss shear modulus Ga” of the adhesion layer AP to the storage shear modulus Ga’ is 0.1 to 2.0.

13. A mounting structure, comprising

a first circuit member, and a second circuit member mounted on the first circuit member,

the second circuit member comprising:

an element having a functional region;

a cover disposed opposite to the functional region; and

a rib formed to surround the functional region, for providing a space between the functional region and the cover,

the cover being tabular and including a sheet S having a thickness of 100μm or less,

the sheet S having a tensile elastic modulus Es at 175°C of 10GPa or more.

14. The mounting structure of claim 13, further comprising a resin encapsulant encapsulating the second circuit member.

15.A method for producing a mounting structure, comprising steps of:

(i) preparing a first circuit member and a second circuit member; and

(ii) mounting the second circuit member on the first circuit member,

the second circuit member comprising:

an element having a functional region;

a cover disposed opposite to the functional region; and

a rib formed to surround the functional region, for providing a space between the functional region and the cover;

the cover being tabular and including a sheet S having a thickness of 100μm or less,

the sheet S having a tensile elastic modulus Es at 175°C of 10GPa or more.

16. The method for producing a mounting structure of claim 15, wherein the second circuit member prepared in the step (i) includes a resin encapsulant encapsulating the second circuit member.

17. The method for producing a mounting structure of claim 15 or 16, further comprising a step of: (iii) encapsulating the second circuit member mounted on the first circuit member, with a resin encapsulant.